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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	562
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFcBGA Rev 2 (33x33)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-6ffa1020c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-6ffa1020c</a>

## Architecture Overview

The LatticeSC architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR). The upper left and upper right corners of the devices contain SERDES blocks and their associated PCS blocks, as shown in Figure 2-1.

Top left and top right corner of the device contain blocks of SERDES. Each block of SERDES contains four channels (quad). Each channel contains a single serializer and de-serializer, synchronization and word alignment logic. The SERDES quad connects with the Physical Coding Sub-layer (PCS) blocks that contain logic to simultaneously perform alignment, coding, de-coding and other functions. The SERDES quad block has separate supply, ground and reference voltage pins.

The PICs contain logic to facilitate the conditioning of signals to and from the I/O before they leave or enter the FPGA fabric. The block provides DDR and shift register capabilities that act as a gearbox between high speed I/O and the FPGA fabric. The blocks also contain programmable Adaptive Input Logic that adjusts the delay applied to signals as they enter the device to optimize setup and hold times and ensure robust performance.

sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM, ROM or FIFO. These blocks have dedicated logic to simplify the implementation of FIFOs.

The PFU, PIC and EBR blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. These blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

The corners contain the sysCLOCK Analog Phase Locked Loop (PLL) and Delay Locked Loop (DLL) Blocks. The PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeSC architecture provides eight analog PLLs per device and 12 DLLs. The DLLs provide a simple delay capability and can also be used to calibrate other delays within the device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The system bus simplifies the connections of the external microprocessor to the device for tasks such as SERDES and PCS configuration or interface to the general FPGA logic. The LatticeSC devices use 1.2V as their core voltage operation with 1.0V operation also possible.

## PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

**Table 2-4. PFU Modes of Operation**

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x 1

## Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

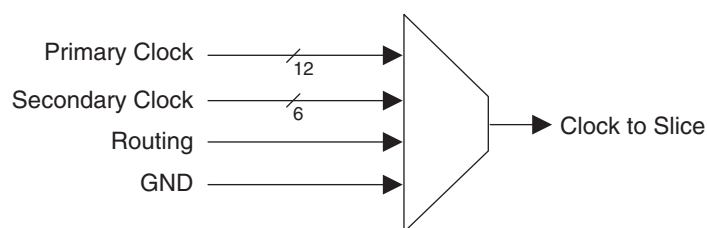
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

## sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

**Figure 2-4. Slice Clock Selection**



Note: GND is available to switch off the network.

## Primary Clock Sources

LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

Figure 2-26. LatticeSC Banks

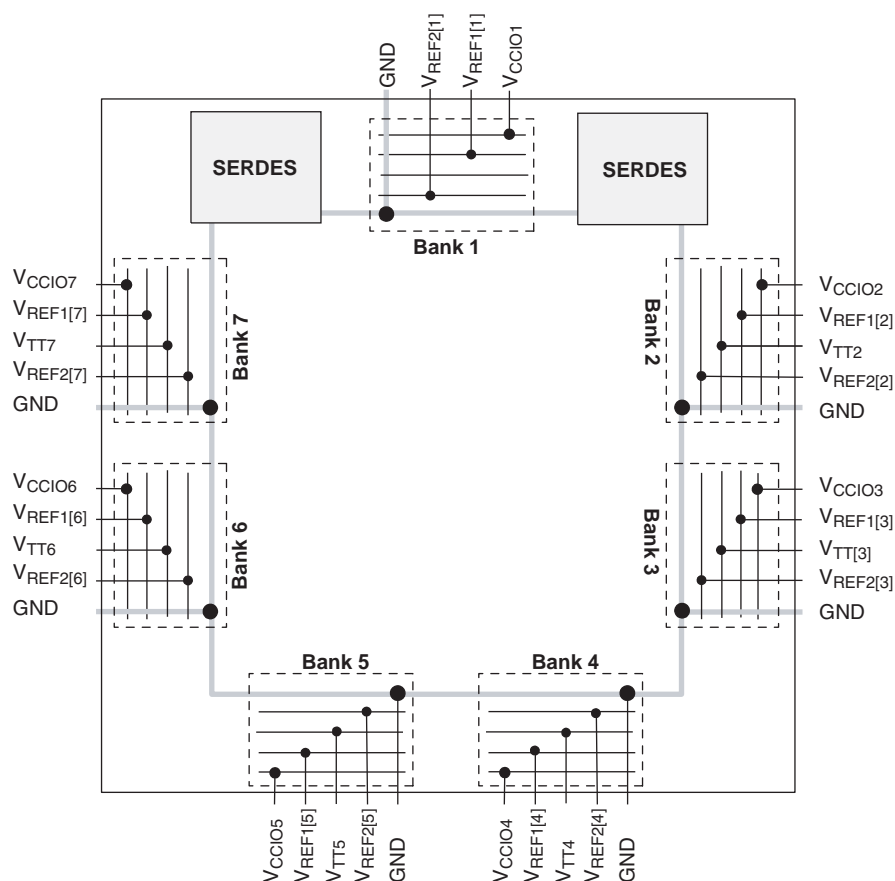


Table 2-7. Maximum Number of I/Os Per Bank in LatticeSC Family

Device	LFSC/M15	LFSC/M25	LFSC/M40	LFSC/M80	LFSC/M115
Bank1	104	80	136	80	136
Bank2	28	36	60	96	136
Bank3	60	84	96	132	156
Bank4	72	100	124	184	208
Bank5	72	100	124	184	208
Bank6	60	84	96	132	156
Bank7	28	36	60	96	136

Note: Not all the I/Os of the Banks are available in all the packages

The LatticeSC devices contain three types of PURESPEED I/O buffers:

1. **Left and Right Sides (Banks 2, 3, 6 and 7)**

These buffers can support LVCMOS standards up to 2.5V. A differential output driver (for LVDS and RSFS) is provided on all primary PIO pairs (A and B) and differential receivers are available on all pairs. Complimentary drivers are available. Adaptive input logic is available on PIOs A or C.

2. **Top Side (Bank 1)**

These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but differential drivers for LVDS and RSFS are not available. Adaptive input logic is not available on this side. Complimentary output drivers are available.

### Differential Input Termination

The LatticeSC device allows two types of differential termination. The first is a single resistor across the differential inputs. The second is a center-tapped system where each input is terminated to the on-chip termination bus  $V_{CMT}$ . The  $V_{CMT}$  bus is DC-coupled through an internal capacitor to ground.

Figure 2-29 shows the differential termination schemes and Table 2-9 shows the nominal values of the termination resistors.

**Figure 2-29. Differential Termination Scheme**

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Differential termination		
Differential and common mode termination		

### Calibration

There are two calibration sources that are associated with the termination scheme used in the LatticeSC devices:

- **DIFFR** – This pin occurs in each bank that supports differential drivers and must be connected through a 1K+/-1% resistor to ground if differential outputs are used. Note that differential drivers are not supported in banks 1, 4 and 5.
- **XRES** – There is one of these pins per device. It is used for several functions including calibrating on-chip termination. This pin should always be connected through a 1K+/-1% resistor to ground.

The LatticeSC devices support two modes of calibration:

- **Continuous** – In this mode the SC devices continually calibrate the termination resistances. Calibration happens several times a second. Using this mode ensures that termination resistances remain calibrated as the silicon junction temperature changes.
- **User Request** – In this mode the calibration circuit operates continuously. However, the termination resistor values are only updated on the assertion of the calibration\_update signal available to the core logic.

For more information on calibration, refer to the details of additional technical documentation at the end of this data sheet.

### Hot Socketing

The LatticeSC devices have been carefully designed to ensure predictable behavior during power-up and power-down. To ensure proper power sequencing, care must be taken during power-up and power-down as described below. During power-up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits,

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## Density Shifting

The LatticeSC family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

## Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
$t_{\text{RAMP}}$	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/ $\mu$ s
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

## Hot Socketing Specifications<sup>1</sup>

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
$I_{\text{DK}}$	Programmable and dedicated Input or I/O leakage current <sup>2, 3, 4, 5, 6</sup>	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	$\pm 1500$	$\mu$ A
$I_{\text{HDIN}}$	SERDES average input current when device powered down and inputs driven <sup>7</sup>		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5.  $I_{\text{DK}}$  is additive to  $I_{\text{PU}}$ ,  $I_{\text{PD}}$  or  $I_{\text{BH}}$ .
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

## DC Electrical Characteristics<sup>5</sup>

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min. <sup>3</sup>	Typ.	Max.	Units
$I_{\text{IL}}, I_{\text{IH}}^1$	Input or I/O Low leakage	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	10	$\mu$ A
$I_{\text{PU}}$	I/O Active Pull-up Current	$0 \leq V_{\text{IN}} \leq 0.7 V_{\text{CCIO}}$	-30	—	-210	$\mu$ A
$I_{\text{PD}}$	I/O Active Pull-down Current	$V_{\text{IL}} (\text{MAX}) \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	30	—	210	$\mu$ A
$I_{\text{BHLS}}$	Bus Hold Low Sustaining Current	$V_{\text{IN}} = V_{\text{IL}} (\text{MAX})$	30	—	—	$\mu$ A
$I_{\text{BHHS}}$	Bus Hold High Sustaining Current	$V_{\text{IN}} = 0.7 V_{\text{CCIO}}$	-30	—	—	$\mu$ A
$I_{\text{BHLO}}$	Bus Hold Low Overdrive Current	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	210	$\mu$ A
$I_{\text{BHLH}}$	Bus Hold High Overdrive Current	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	-210	$\mu$ A
$I_{\text{CL}}$	PCI Low Clamp Current	$-3 < V_{\text{IN}} \leq -1$	$-25 + (V_{\text{IN}} + 1)/0.015$	—	—	mA
$I_{\text{CH}}$	PCI High Clamp Current	$V_{\text{CC}} + 4 > V_{\text{IN}} \geq V_{\text{CC}} + 1$	$25 + (V_{\text{IN}} - V_{\text{CC}} - 1)/0.015$	—	—	mA
$V_{\text{BHT}}$	Bus Hold trip Points	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	$V_{\text{IL}} (\text{MAX})$	—	$V_{\text{IH}} (\text{MIN})$	V
C1	I/O Capacitance <sup>2</sup>	$V_{\text{CCIO}} = 3.3\text{V}, 2.5\text{V}, 1.8\text{V}, 1.5\text{V}, 1.2\text{V},$ $V_{\text{CC}} = 1.2\text{V}, V_{\text{CCIP2}} = 1.2\text{V},$ $V_{\text{CCAUX}} = 2.5, V_{\text{IO}} = 0 \text{ to } V_{\text{IH}} (\text{MAX})$	—	8	—	pf
C3 <sup>2</sup>	Dedicated Input Capacitance <sup>2</sup>	$V_{\text{CCIO}} = 3.3\text{V}, 2.5\text{V}, 1.8\text{V}, 1.5\text{V}, 1.2\text{V},$ $V_{\text{CC}} = 1.2\text{V}, V_{\text{CCIP2}} = 1.2\text{V},$ $V_{\text{CCAUX}} = 2.5, V_{\text{IO}} = 0 \text{ to } V_{\text{IH}} (\text{MAX})$	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2.  $T_{\text{A}} = 25^{\circ}\text{C}$ ,  $f = 1.0\text{MHz}$
3.  $I_{\text{PU}}$ ,  $I_{\text{PD}}$ ,  $I_{\text{BHLS}}$  and  $I_{\text{BHHS}}$  have minimum values of 15 or -15 $\mu$ A if  $V_{\text{CCIO}}$  is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

**LatticeSC/M Family Timing Adders (Continued)**

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.024	-0.106	0.019	-0.004	0.016	0.099	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.074	-0.134	0.08	-0.022	0.088	0.089	ns
LVC MOS18_OD	LVC MOS 1.8 open drain	0.002	-0.206	0	-0.196	-0.002	-0.221	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	-0.344	-0.164	-0.379	-0.186	-0.412	-0.209	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	-0.125	-0.137	-0.145	-0.157	-0.164	-0.176	ns
LVC MOS15_12mA	LVC MOS 1.5 12mA drive	-0.027	-0.166	-0.043	-0.07	-0.059	0.026	ns
LVC MOS15_16mA	LVC MOS 1.5 16mA drive	0.025	-0.195	0.013	-0.089	0.003	0.017	ns
LVC MOS15_OD	LVC MOS 1.5 open drain	-0.047	-0.267	-0.067	-0.267	-0.087	-0.299	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	-0.473	-0.293	-0.505	-0.317	-0.537	-0.34	ns
LVC MOS12_4mA	LVC MOS 1.2 4mA drive	-0.218	-0.239	-0.25	-0.271	-0.28	-0.303	ns
LVC MOS12_8mA	LVC MOS 1.2 8mA drive	-0.109	-0.269	-0.143	-0.181	-0.176	-0.093	ns
LVC MOS12_12mA	LVC MOS 1.2 12mA drive	-0.054	-0.3	-0.085	-0.203	-0.114	-0.106	ns
LVC MOS12_OD	LVC MOS 1.2 open drain	-0.126	-0.371	-0.166	-0.398	-0.204	-0.43	ns
PCI33	PCI	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX33	PCI-X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX15	PCI-X 1.5	0.208	0.227	0.233	0.312	0.259	0.398	ns
AGP1X33	AGP-1X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
AGP2X33	AGP-2X	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns



**Signal Descriptions (Cont.)**

Signal Name	I/O	Description
PROBE_GND	—	GND signal - Connected to internal VSS node. Can be used for feedback to control an external board power converter. Can be unconnected if not used.
<b>PLL and Clock Functions (Used as user-programmable I/O pins when not in use for PLL, DLL or clock pins.)</b>		
[LOC]_PLL[T, C]_FB_[A/B]	I	PLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T, C] indicates whether input is true or complement. [A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_FB_[C, D, E, F]	I	DLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners.
[LOC]_PLL[T, C]_IN[A/B]	I	PLL reference clock input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T, C] indicates whether input is true or complement. [A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_IN[C, D, E, F]		DLL reference clock inputs. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners. PCKLxy_[0:3] can drive primary clocks, edge clocks, and CLKDIVs. PCLKxy_[4:7] can only drive edge clocks.
PCLKxy_z		General clock inputs. x indicates whether T (true) or C (complement). y indicates the I/O bank the clock is associated with. z indicates the clock number within a bank.
<b>Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)</b>		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin - Test Data out pin used to shift data out of device using 1149.1.
<b>Configuration Pads (Dedicated pins. Used during sysCONFIG.)</b>		
M[3:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled that will pull the I/O above 1.5V.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.

**LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA<sup>1, 2</sup> (Cont.)**

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
R29	PR28B	3		PR31B	3	
P29	PR28A	3		PR31A	3	
P27	PR27C	3	PCLKT3_3	PR30C	3	PCLKT3_3
N29	PR27B	3		PR30B	3	
N28	PR27A	3		PR30A	3	
R25	PR26D	3	PCLKC3_1	PR29D	3	PCLKC3_1
R26	PR26C	3	PCLKT3_1	PR29C	3	PCLKT3_1
R28	PR26B	3	PCLKC3_0	PR29B	3	PCLKC3_0
P28	PR26A	3	PCLKT3_0	PR29A	3	PCLKT3_0
N27	PR24D	2	PCLKC2_2	PR27D	2	PCLKC2_2
P26	PR24C	2	PCLKT2_2	PR27C	2	PCLKT2_2
L30	PR24B	2	PCLKC2_0	PR27B	2	PCLKC2_0
K30	PR24A	2	PCLKT2_0	PR27A	2	PCLKT2_0
J30	PR23B	2	PCLKC2_1	PR26B	2	PCLKC2_1
H30	PR23A	2	PCLKT2_1	PR26A	2	PCLKT2_1
M26	PR22D	2	DIFFR_2	PR25D	2	DIFFR_2
M25	PR22C	2	VREF1_2	PR25C	2	VREF1_2
G29	PR22B	2		PR25B	2	
F29	PR22A	2		PR25A	2	
H28	PR19D	2		PR22D	2	
J28	PR19C	2		PR22C	2	
E30	PR19B	2		PR22B	2	
E29	PR19A	2		PR22A	2	
L26	PR18D	2	VREF2_2	PR18D	2	VREF2_2
L25	PR18C	2		PR18C	2	
F28	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G28	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
K26	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
K25	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
D30	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
D29	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
G26	PR15D	2		PR16D	2	
H26	PR15C	2		PR16C	2	
E28	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
D28	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
J25	VCCJ	-		VCCJ	-	
H25	TDO	-	TDO	TDO	-	TDO
J26	TMS	-		TMS	-	
G25	TCK	-		TCK	-	
G24	TDI	-		TDI	-	
F26	PROGRAMN	1		PROGRAMN	1	
H24	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
F25	CCLK	1		CCLK	1	
D27	VCC12	-		VCC12	-	
E26	VCC12	-		VCC12	-	

**LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup> (Cont.)**

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH11	PB57D	4		PB79D	4	
AN13	PB58A	4	PCLKT4_3	PB80A	4	PCLKT4_3
AN12	PB58B	4	PCLKC4_3	PB80B	4	PCLKC4_3
AD14	PB58C	4	PCLKT4_4	PB80C	4	PCLKT4_4
AD15	PB58D	4	PCLKC4_4	PB80D	4	PCLKC4_4
AP13	PB61A	4		PB73A	4	
AP12	PB61B	4		PB73B	4	
AK13	PB61C	4		PB73C	4	
AK12	PB61D	4		PB73D	4	
AP11	PB62A	4		PB83A	4	
AP10	PB62B	4		PB83B	4	
AN11	PB63A	4		PB99A	4	
AN10	PB63B	4		PB99B	4	
AF14	PB63C	4		PB99C	4	
AF13	PB63D	4		PB99D	4	
AM10	PB67A	4		PB101A	4	
AM9	PB67B	4		PB101B	4	
AE14	PB67C	4		PB101C	4	
AE13	PB67D	4		PB101D	4	
AP9	PB69A	4		PB104A	4	
AP8	PB69B	4		PB104B	4	
AK11	PB69C	4		PB104C	4	
AK10	PB69D	4		PB104D	4	
AL10	PB70A	4		PB107A	4	
AL9	PB70B	4		PB107B	4	
AF12	PB70C	4		PB107C	4	
AF11	PB70D	4		PB107D	4	
AN9	PB73A	4		PB109A	4	
AN8	PB73B	4		PB109B	4	
AG11	PB73C	4		PB109C	4	
AG10	PB73D	4		PB109D	4	
AP7	PB74A	4		PB111A	4	
AP6	PB74B	4		PB111B	4	
AG13	PB74C	4		PB111C	4	
AG12	PB74D	4		PB111D	4	
AN7	PB75A	4		PB113A	4	
AN6	PB75B	4		PB113B	4	
AK9	PB75C	4		PB113C	4	
AK8	PB75D	4		PB113D	4	
AP5	PB77A	4		PB115A	4	
AP4	PB77B	4		PB115B	4	
AD11	PB77C	4		PB115C	4	
AE11	PB77D	4		PB115D	4	
AM7	PB78A	4		PB117A	4	
AM6	PB78B	4		PB117B	4	

**LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup> (Cont.)**

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AD8	PR65C	3		PR89C	3	
AJ3	PR65B	3		PR89B	3	
AH3	PR65A	3		PR89A	3	
AD7	PR62D	3		PR86D	3	
AC7	PR62C	3		PR86C	3	
AJ2	PR62B	3		PR86B	3	
AH2	PR62A	3		PR86A	3	
AF6	PR61D	3		PR85D	3	
AF5	PR61C	3		PR85C	3	
AF4	PR61B	3		PR85B	3	
AE4	PR61A	3		PR85A	3	
AD6	PR60D	3		PR84D	3	
AC6	PR60C	3		PR84C	3	
AG2	PR60B	3		PR84B	3	
AF2	PR60A	3		PR84A	3	
AC8	PR58D	3		PR82D	3	
AB8	PR58C	3		PR82C	3	
AK1	PR58B	3		PR82B	3	
AJ1	PR58A	3		PR82A	3	
AB10	PR57D	3		PR81D	3	
AA10	PR57C	3		PR81C	3	
AF3	PR57B	3		PR81B	3	
AE3	PR57A	3		PR81A	3	
AE5	PR56D	3		PR80D	3	
AD5	PR56C	3		PR80C	3	
AE2	PR56B	3		PR80B	3	
AD2	PR56A	3		PR80A	3	
AC5	PR53D	3		PR78D	3	
AB5	PR53C	3		PR78C	3	
AF1	PR53B	3		PR78B	3	
AE1	PR53A	3		PR78A	3	
AA11	PR52D	3		PR77D	3	
Y11	PR52C	3		PR77C	3	
AC4	PR52B	3		PR77B	3	
AB4	PR52A	3		PR77A	3	
AA8	PR51D	3	DIFFR_3	PR76D	3	DIFFR_3
AA9	PR51C	3		PR76C	3	
AC3	PR51B	3		PR76B	3	
AB3	PR51A	3		PR76A	3	
AA7	PR49D	3		PR65D	3	
Y7	PR49C	3		PR65C	3	
AA2	PR49B	3		PR65B	3	
Y2	PR49A	3		PR65A	3	
AA6	PR48D	3		PR63D	3	
Y6	PR48C	3		PR63C	3	

**LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup> (Cont.)**

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC19	VTT_5	5		VTT_5	5	
AC20	VTT_5	5		VTT_5	5	
AD22	VTT_5	5		VTT_5	5	
AB24	VTT_6	6		VTT_6	6	
W23	VTT_6	6		VTT_6	6	
Y23	VTT_6	6		VTT_6	6	
N24	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
T23	VTT_7	7		VTT_7	7	
M12	VDDAX25_R	-		VDDAX25_R	-	
M23	VDDAX25_L	-		VDDAX25_L	-	
Y16	GND	-		GND	-	
Y14	GND	-		GND	-	
N21	VCC12	-		VCC12	-	
P22	VCC12	-		VCC12	-	
AA22	VCC12	-		VCC12	-	
AB21	VCC12	-		VCC12	-	
AB14	VCC12	-		VCC12	-	
AA13	VCC12	-		VCC12	-	
P13	VCC12	-		VCC12	-	
N14	VCC12	-		VCC12	-	
G26	NC	-		NC	-	
G9	NC	-		NC	-	
J12	NC	-		NC	-	
H12	NC	-		NC	-	
H23	NC	-		NC	-	
J23	NC	-		NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).

2. The LatticeSC/M40 and LatticeSC/M80 in an 1152-pin package support a 32-bit MPI interface.

**LFSC/M115 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup>**

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AP27	PB26A	5	
AP26	PB26B	5	
AK25	PB26C	5	
AK24	PB26D	5	
AN25	PB29A	5	
AN24	PB29B	5	
AE22	PB29C	5	
AE21	PB29D	5	
AM26	PB31A	5	
AM25	PB31B	5	
AF22	PB31C	5	
AF21	PB31D	5	
AN23	PB47A	5	
AN22	PB47B	5	
AP23	PB57A	5	
AP22	PB57B	5	
AG21	PB57C	5	
AG20	PB57D	5	
AP25	PB50A	5	PCLKT5_3
AP24	PB50B	5	PCLKC5_3
AD21	PB50C	5	PCLKT5_4
AD20	PB50D	5	PCLKC5_4
AL23	PB51A	5	PCLKT5_5
AL22	PB51B	5	PCLKC5_5
AH24	PB51C	5	
AH23	PB51D	5	
AM23	PB53A	5	PCLKT5_0
AM22	PB53B	5	PCLKC5_0
AJ24	PB53C	5	
AJ23	PB53D	5	VREF2_5
AN21	PB54A	5	PCLKT5_1
AN20	PB54B	5	PCLKC5_1
AE19	PB54C	5	PCLKT5_6
AD19	PB54D	5	PCLKC5_6
AK21	PB55A	5	PCLKT5_2
AK20	PB55B	5	PCLKC5_2
AK23	PB55C	5	PCLKT5_7
AK22	PB55D	5	PCLKC5_7
AL20	PB58A	5	
AL19	PB58B	5	
AG19	PB58C	5	
AF19	PB58D	5	
AP21	PB61A	5	

**LFSC/M115 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup>**

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AL4	PR117B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AL3	PR117A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AD10	PR116D	3	
AD9	PR116C	3	
AH4	PR116B	3	
AJ4	PR116A	3	
AK5	PR115D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AJ5	PR115C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AM1	PR115B	3	
AL1	PR115A	3	
AH5	PR112D	3	
AG5	PR112C	3	
AL2	PR112B	3	
AK2	PR112A	3	
AB9	PR109D	3	
AC9	PR109C	3	
AH1	PR109B	3	
AG1	PR109A	3	
AE8	PR107D	3	VREF2_3
AD8	PR107C	3	
AJ3	PR107B	3	
AH3	PR107A	3	
AD7	PR104D	3	
AC7	PR104C	3	
AJ2	PR104B	3	
AH2	PR104A	3	
AF6	PR103D	3	
AF5	PR103C	3	
AF4	PR103B	3	
AE4	PR103A	3	
AD6	PR99D	3	
AC6	PR99C	3	
AG2	PR99B	3	
AF2	PR99A	3	
AC8	PR98D	3	
AB8	PR98C	3	
AK1	PR98B	3	
AJ1	PR98A	3	
AB10	PR96D	3	
AA10	PR96C	3	
AF3	PR96B	3	
AE3	PR96A	3	
AE5	PR94D	3	

**LFSC/M115 Logic Signal Connections: 1152 fcBGA<sup>1, 2</sup>**

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AD5	PR94C	3	
AE2	PR94B	3	
AD2	PR94A	3	
AC5	PR92D	3	
AB5	PR92C	3	
AF1	PR92B	3	
AE1	PR92A	3	
AA11	PR91D	3	
Y11	PR91C	3	
AC4	PR91B	3	
AB4	PR91A	3	
AA8	PR90D	3	DIFFR_3
AA9	PR90C	3	
AC3	PR90B	3	
AB3	PR90A	3	
AA7	PR79D	3	
Y7	PR79C	3	
AA2	PR79B	3	
Y2	PR79A	3	
AA6	PR77D	3	
Y6	PR77C	3	
Y4	PR77B	3	
W4	PR77A	3	
W11	PR74D	3	
V11	PR74C	3	
W2	PR74B	3	
V2	PR74A	3	
W9	PR71D	3	
V9	PR71C	3	
V1	PR71B	3	
U1	PR71A	3	
W10	PR70D	3	
V10	PR70C	3	
U2	PR70B	3	
T2	PR70A	3	
Y8	PR69D	3	
W8	PR69C	3	VREF1_3
W5	PR69B	3	
V5	PR69A	3	
V7	PR66D	3	PCLKC3_2
U7	PR66C	3	PCLKT3_2
T1	PR66B	3	
R1	PR66A	3	



**LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA<sup>1, 2</sup> (Cont.)**

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AP8	PB117D	4		PB131D	4	
AY3	PB119A	4		PB133A	4	
AW3	PB119B	4		PB133B	4	
AR6	PB119C	4		PB133C	4	
AR5	PB119D	4		PB133D	4	
AU5	PB120A	4		PB134A	4	
AV5	PB120B	4		PB134B	4	
AL12	PB120C	4		PB134C	4	
AL11	PB120D	4		PB134D	4	
AV3	PB121A	4		PB135A	4	
AV4	PB121B	4		PB135B	4	
AN9	PB121C	4		PB135C	4	
AN8	PB121D	4		PB135D	4	
AW1	PB123A	4		PB138A	4	
AY1	PB123B	4		PB138B	4	
AK14	PB123C	4	VREF1_4	PB138C	4	VREF1_4
AK13	PB123D	4		PB138D	4	
AV2	PB124A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB139A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AW2	PB124B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB139B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AM10	PB124C	4		PB139C	4	
AM9	PB124D	4		PB139D	4	
AV1	PB125A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB141A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AU1	PB125B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB141B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AL10	PB125C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB141C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AL9	PB125D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB141D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AT3	PROBE_VCC	-		PROBE_VCC	-	
AU2	PROBE_GND	-		PROBE_GND	-	
AP7	PR95D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR117D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AN7	PR95C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR117C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AR3	PR95B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR117B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AR4	PR95A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR117A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AP6	PR94D	3		PR116D	3	
AN6	PR94C	3		PR116C	3	
AT2	PR94B	3		PR116B	3	
AR2	PR94A	3		PR116A	3	
AM6	PR93D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR115D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AL6	PR93C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR115C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AP5	PR93B	3		PR115B	3	
AN5	PR93A	3		PR115A	3	
AL8	PR91D	3		PR112D	3	
AK8	PR91C	3		PR112C	3	
AP2	PR91B	3		PR112B	3	
AN2	PR91A	3		PR112A	3	
AJ12	PR90D	3		PR109D	3	
AH12	PR90C	3		PR109C	3	

**LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA<sup>1,2</sup> (Cont.)**

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V21	VCC	-		VCC	-	
V22	VCC	-		VCC	-	
V23	VCC	-		VCC	-	
V25	VCC	-		VCC	-	
V27	VCC	-		VCC	-	
W17	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
W22	VCC	-		VCC	-	
W24	VCC	-		VCC	-	
W26	VCC	-		VCC	-	
Y16	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	
Y23	VCC	-		VCC	-	
Y25	VCC	-		VCC	-	
Y27	VCC	-		VCC	-	
AG22	VCC12	-		VCC12	-	
AG26	VCC12	-		VCC12	-	
T17	VCC12	-		VCC12	-	
T21	VCC12	-		VCC12	-	
T22	VCC12	-		VCC12	-	
T26	VCC12	-		VCC12	-	
U16	VCC12	-		VCC12	-	
U27	VCC12	-		VCC12	-	
AC15	VCCAUX	-		VCCAUX	-	
AC28	VCCAUX	-		VCCAUX	-	
AD15	VCCAUX	-		VCCAUX	-	
AD28	VCCAUX	-		VCCAUX	-	
AE15	VCCAUX	-		VCCAUX	-	
AE28	VCCAUX	-		VCCAUX	-	
AF15	VCCAUX	-		VCCAUX	-	
AF28	VCCAUX	-		VCCAUX	-	
AG15	VCCAUX	-		VCCAUX	-	
AG28	VCCAUX	-		VCCAUX	-	
AH14	VCCAUX	-		VCCAUX	-	
AH16	VCCAUX	-		VCCAUX	-	
AH17	VCCAUX	-		VCCAUX	-	
AH18	VCCAUX	-		VCCAUX	-	
AH19	VCCAUX	-		VCCAUX	-	
AH20	VCCAUX	-		VCCAUX	-	
AH23	VCCAUX	-		VCCAUX	-	
AH24	VCCAUX	-		VCCAUX	-	
AH25	VCCAUX	-		VCCAUX	-	
AH26	VCCAUX	-		VCCAUX	-	

**LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA<sup>1, 2</sup> (Cont.)**

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AW25	VCCIO5	-		VCCIO5	-	
AW31	VCCIO5	-		VCCIO5	-	
AW37	VCCIO5	-		VCCIO5	-	
AY22	VCCIO5	-		VCCIO5	-	
AY28	VCCIO5	-		VCCIO5	-	
AY34	VCCIO5	-		VCCIO5	-	
AB39	VCCIO6	-		VCCIO6	-	
AC36	VCCIO6	-		VCCIO6	-	
AD32	VCCIO6	-		VCCIO6	-	
AE40	VCCIO6	-		VCCIO6	-	
AF35	VCCIO6	-		VCCIO6	-	
AG31	VCCIO6	-		VCCIO6	-	
AH39	VCCIO6	-		VCCIO6	-	
AJ36	VCCIO6	-		VCCIO6	-	
AK32	VCCIO6	-		VCCIO6	-	
AL40	VCCIO6	-		VCCIO6	-	
AM35	VCCIO6	-		VCCIO6	-	
AP39	VCCIO6	-		VCCIO6	-	
AR36	VCCIO6	-		VCCIO6	-	
AU40	VCCIO6	-		VCCIO6	-	
AA40	VCCIO7	-		VCCIO7	-	
H36	VCCIO7	-		VCCIO7	-	
J40	VCCIO7	-		VCCIO7	-	
L35	VCCIO7	-		VCCIO7	-	
M39	VCCIO7	-		VCCIO7	-	
P36	VCCIO7	-		VCCIO7	-	
R40	VCCIO7	-		VCCIO7	-	
T31	VCCIO7	-		VCCIO7	-	
U35	VCCIO7	-		VCCIO7	-	
V39	VCCIO7	-		VCCIO7	-	
W32	VCCIO7	-		VCCIO7	-	
Y36	VCCIO7	-		VCCIO7	-	
AA14	VTT_2	2		VTT_2	2	
AA15	VTT_2	2		VTT_2	2	
R12	VTT_2	2		VTT_2	2	
V14	VTT_2	2		VTT_2	2	
AB14	VTT_3	3		VTT_3	3	
AB15	VTT_3	3		VTT_3	3	
AE14	VTT_3	3		VTT_3	3	
AJ13	VTT_3	3		VTT_3	3	
AH21	VTT_4	4		VTT_4	4	
AJ18	VTT_4	4		VTT_4	4	
AJ19	VTT_4	4		VTT_4	4	
AJ20	VTT_4	4		VTT_4	4	
AJ21	VTT_4	4		VTT_4	4	

## Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FF1020C <sup>1</sup>	-7	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FF1020C <sup>1</sup>	-6	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FF1020C <sup>1</sup>	-5	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FC1152C <sup>2</sup>	-7	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FC1152C <sup>2</sup>	-6	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FC1152C <sup>2</sup>	-5	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).2. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FF1020C <sup>1</sup>	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FF1020C <sup>1</sup>	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FF1020C <sup>1</sup>	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FC1152C <sup>2</sup>	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FC1152C <sup>2</sup>	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FC1152C <sup>2</sup>	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).2. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

**Commercial, Cont.**

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FCN1152C <sup>1</sup>	-6	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FCN1152C <sup>1</sup>	-5	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FCN1704C <sup>1</sup>	-6	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FCN1704C <sup>1</sup>	-5	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FFN1704C	-6	Lead-Free Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FFN1704C	-5	Lead-Free Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).